## Vecim: A 289.13GOPS/W RISC-V Vector Co-Processor with Compute-in-Memory Vector Register File for Efficient High-Performance Computing

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### Outline

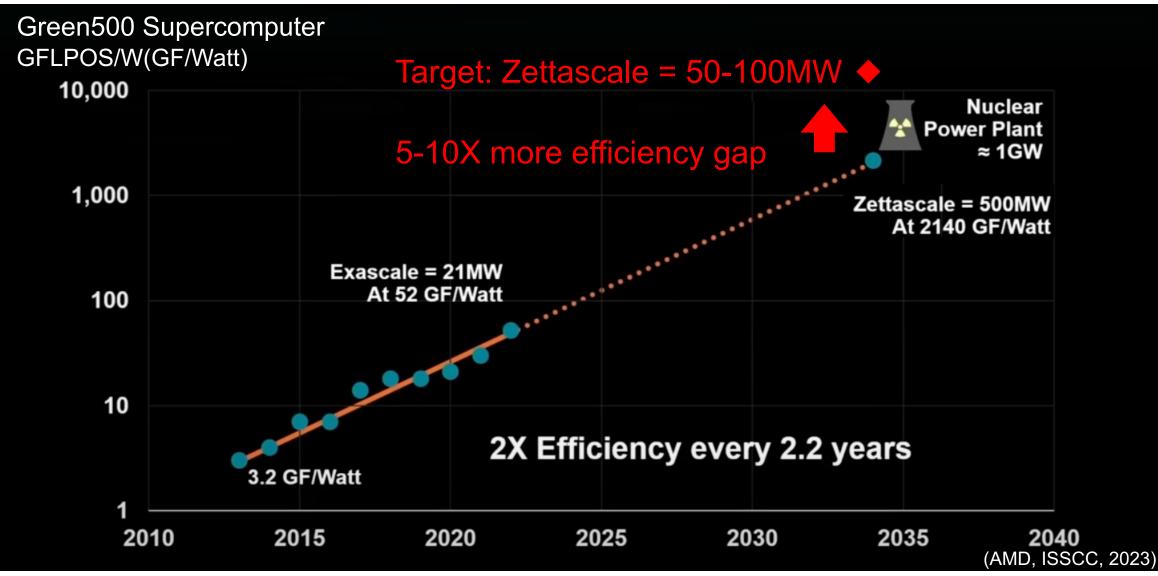
#### Motivation

- Efficiency gap of HPC
- SRAM Compute-in-memory(CIM) application challenges

#### Proposed Vecim Architecture

- Overall architecture
- CIM vector register file (VRF) and multiplication scheme
- Data path and data flow
- Silicon prototype measurements
   Summary

### **Motivation 1: Efficiency Gap of HPC**



# Motivation 1: Efficiency Gap of HPC $Efficiency = OPS/W = \frac{OP}{E_{compute} + E_{others}} \uparrow$ $= \frac{E_{compute}}{E_{compute} + E_{others}} / \frac{E_{compute}}{OP} \downarrow$

Increase the proportion of Compute's energy

- Specialized instruction
- Domain specific hardware
- Datapath and memory optimization

Improve the average <u>Energy</u> consumption of compute <u>OP</u>eration

- Technology scaling
- Lower precision
- Sparsity

• ...

# Motivation 1: Efficiency Gap of HPC $Efficiency = OPS/W = \frac{OP}{E_{compute} + E_{others}} \uparrow$ $= \frac{E_{compute}}{E_{compute} + E_{others}} / \frac{E_{compute}}{OP} \downarrow$

Increase the proportion of Compute's energy Improve the average energy consumption of compute operation

#### This work

- Specialized instruction
- Domain specific hardware
- Datapath and memory optimization
- In memory vector processing

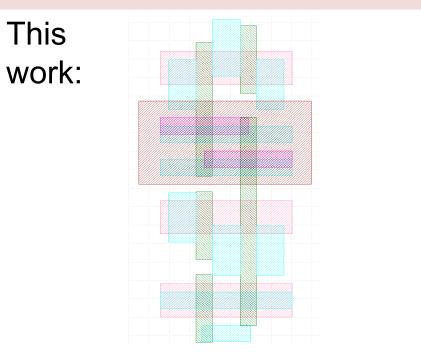
- Technology scaling
- Lower precision
- Sparsity
- Reusing SRAM for compute

#### Explore architectural opportunity CIM provide for general purpose HW.

#### Motivation 2: SRAM CIM application challenges

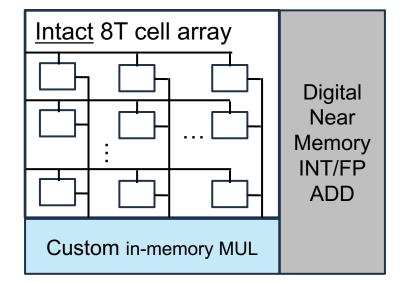
Large area footprint

Low robustness: PVT variation of custom cells, IR drop Low frequency: Longer WL/BL, large adder tree Accuracy loss: ADC, FP conversion/limited window





(Modified layout only for illustration purpose)



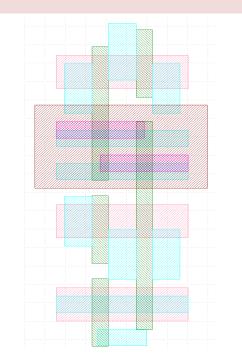
Intact cell array Pipelined digital CIM Near memory FP support

#### Motivation 2: SRAM CIM <u>application</u> challenges

#### Large area footprint

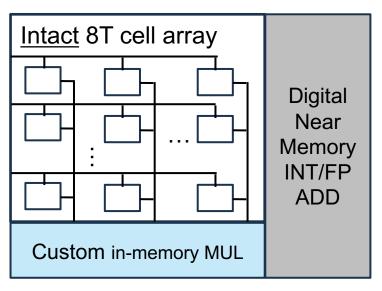
Low robustness Low frequency Accuracy loss

#### Low programmability



#### Use foundry 8T cell

(Modified layout only for illustration purpose)



Intact cell array Pipelined digital CIM Near memory FP support Embed CIM in general purpose architecture / ISA; Show efficiency improvement

→ RISCV vector processor

- → large memory capacity in register files
- $\rightarrow$  Target matrix multiplication

 $\rightarrow$  Our key contribution

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### **Vecim Overall Architecture**

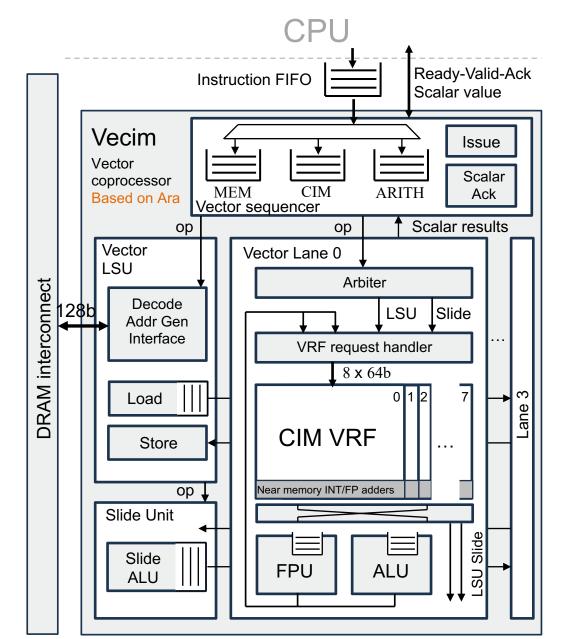
□Based on open sourced [Ara, TVLSI, 2020]

□Instructions from scalar CPU

□64bit/lane/cycle bandwidth DRAM

□Vector Load-Store Unit (LSU)

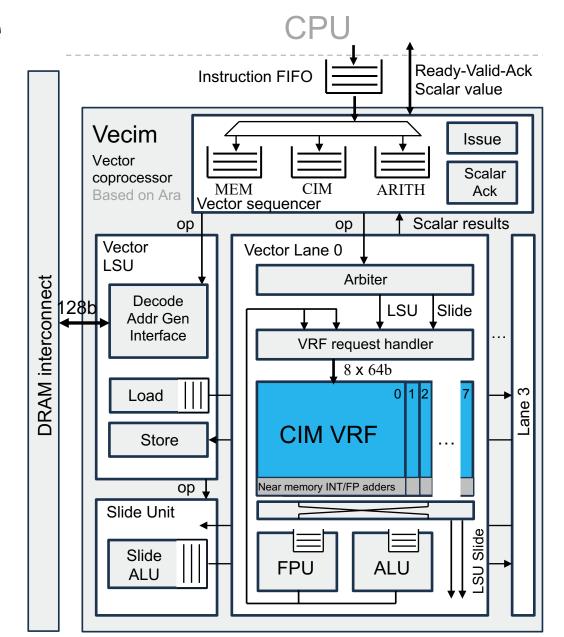
□ Vector Slide Unit



# **Vecim Overall Architecture**

**Our Innovations** 

- □A 1R1W SRAM Vector Register File (VRF)
  - INT8/BF16/FP16 all-digital in-memory multiplication and near-mem addition
  - Double-rate-bit-parallel multiplication
  - Specialized instruction extension



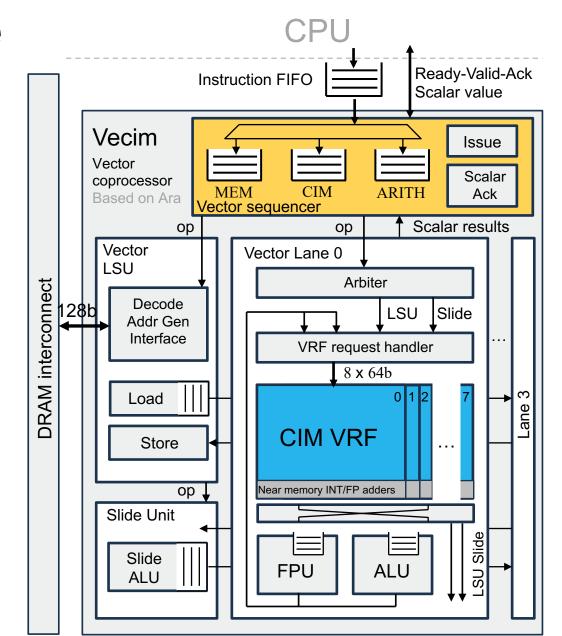
# **Vecim Overall Architecture**

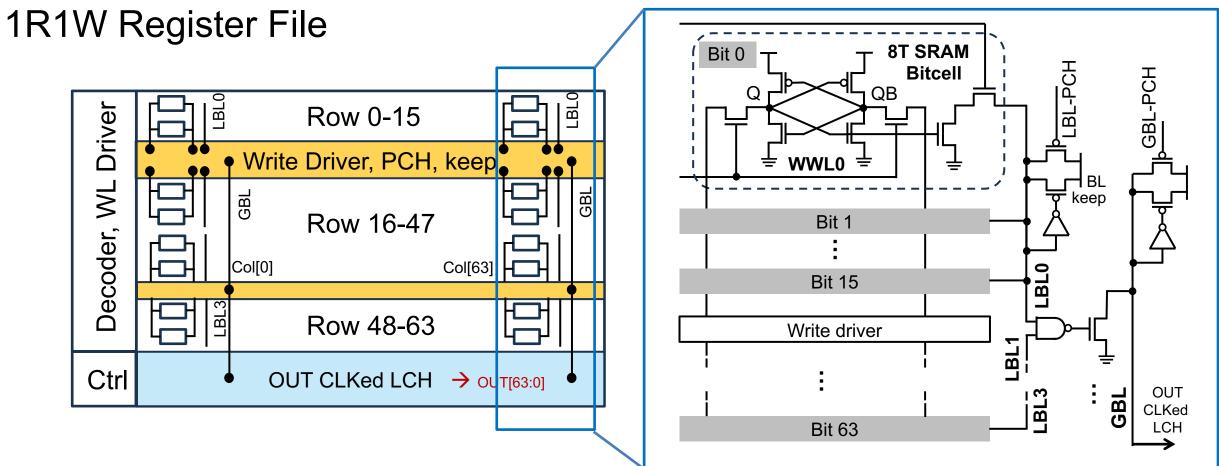
**Our Innovations** 

- □A 1R1W SRAM Vector Register File (VRF)
  - INT8/BF16/FP16 all-digital in-memory multiplication and addition
  - Double-rate-bit-parallel multiplication
  - Specialized instruction extension

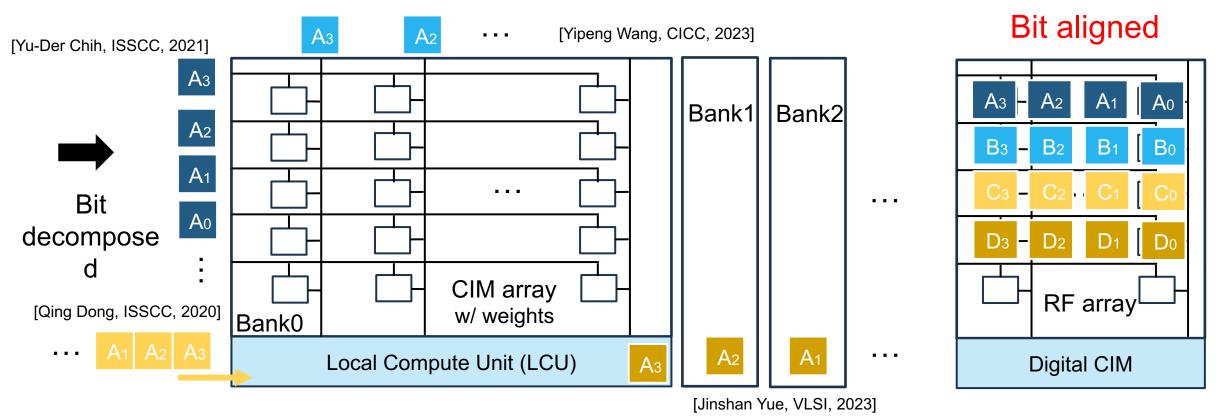
□A dedicated vector sequencer

Light-weight out-of-order execution





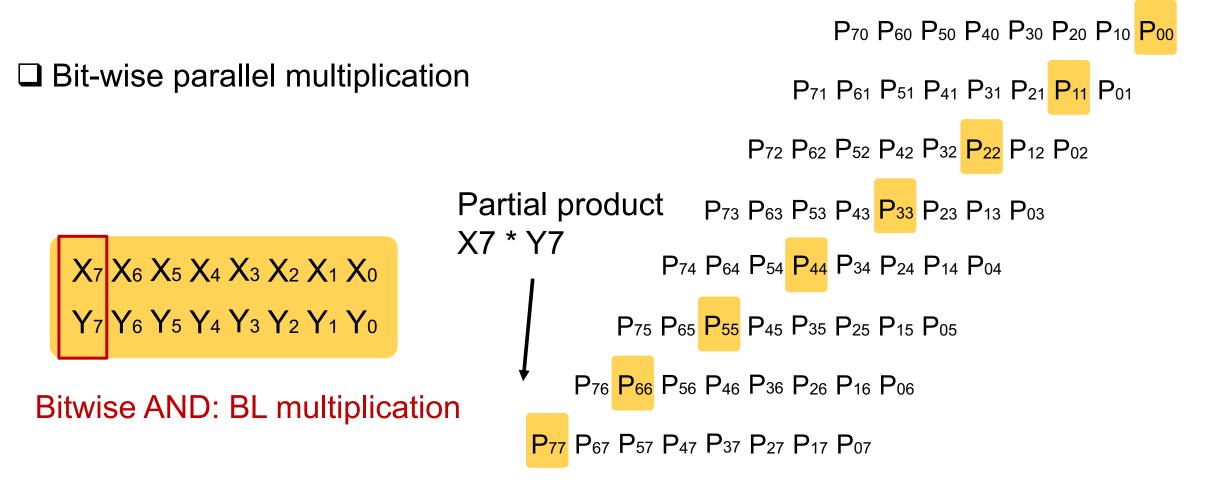
- Decoupled read/write ports for higher throughput
- Lower Vmin to be compatible with core logic

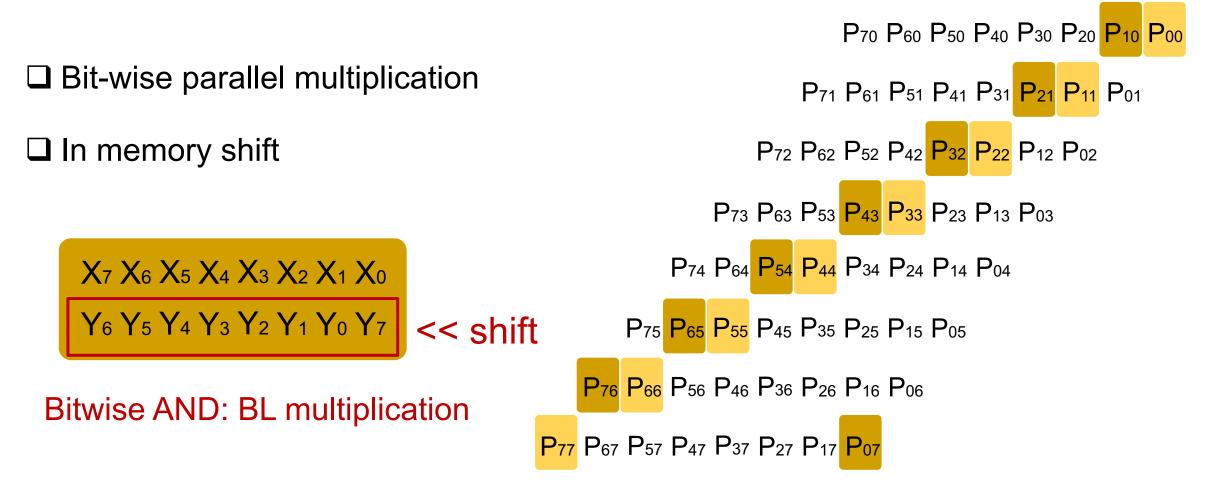


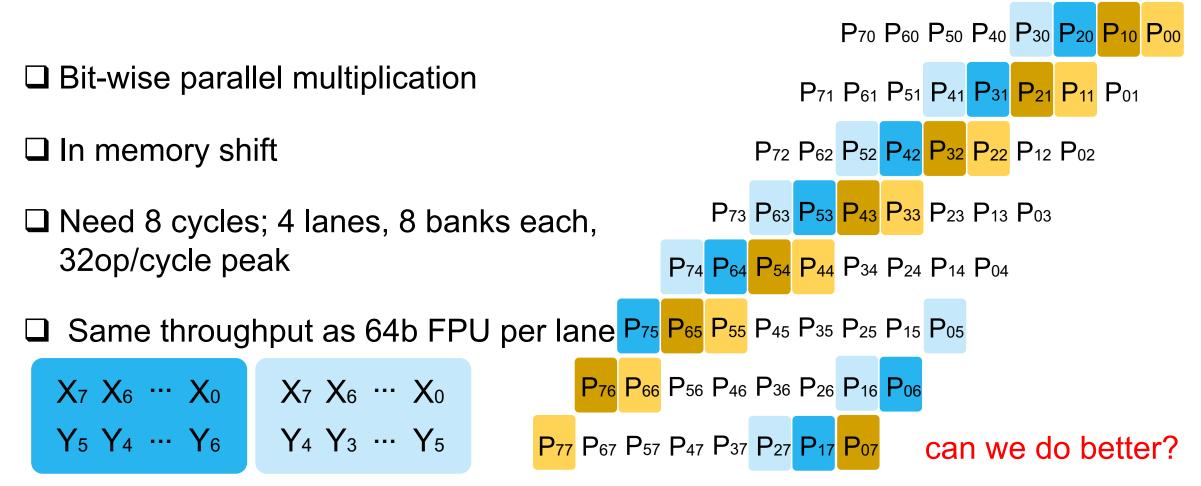
Traditional CIM dataflow for Neural Networks

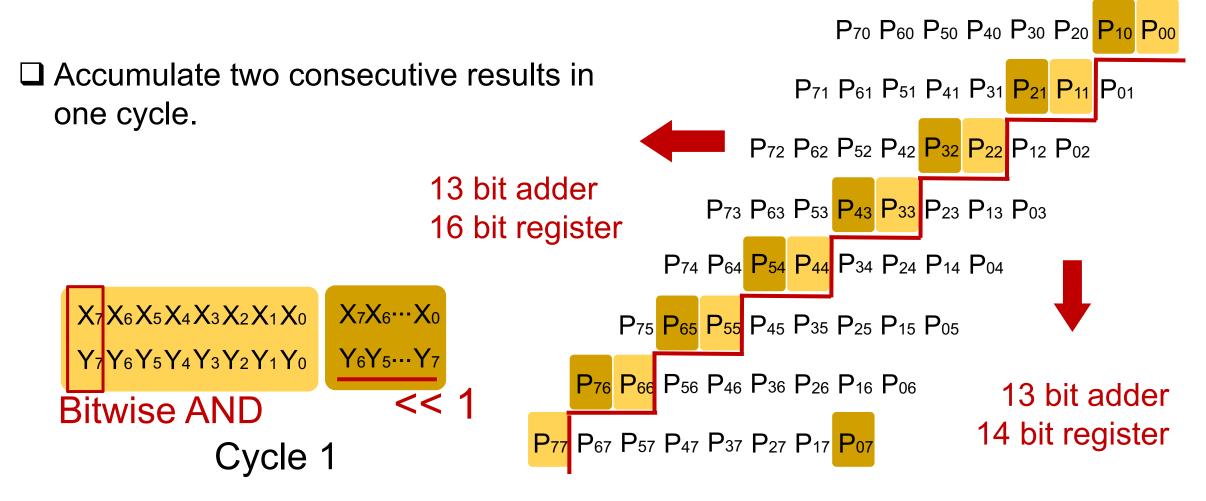
This work

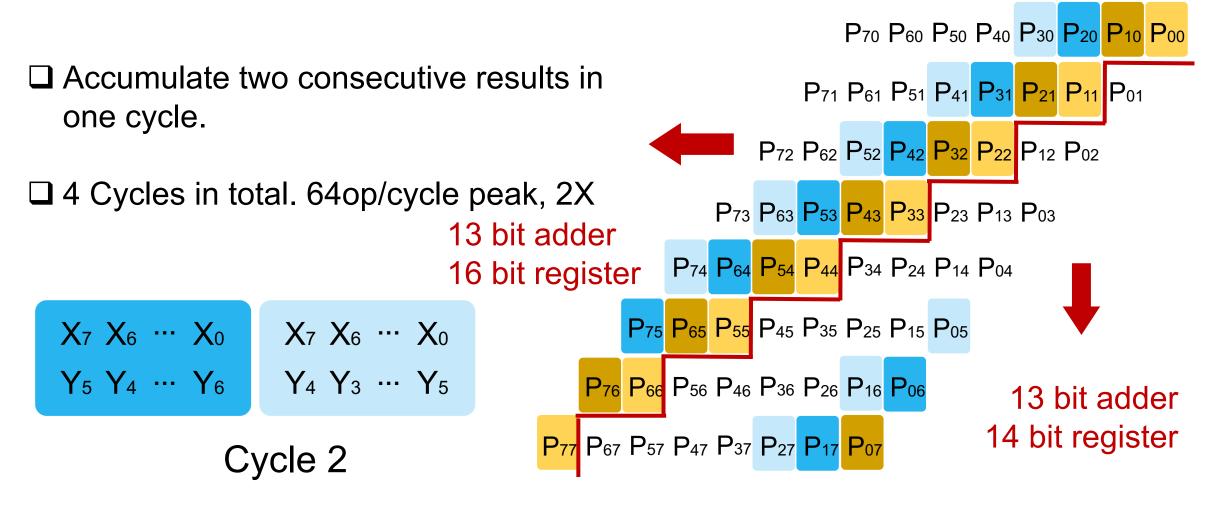
- Activations are bit decomposed to WL/BL/LCU/Banks, either bit-serial or bit-parallel.
- Vector processor only support RF with bit-aligned data layout. New dataflow needed.









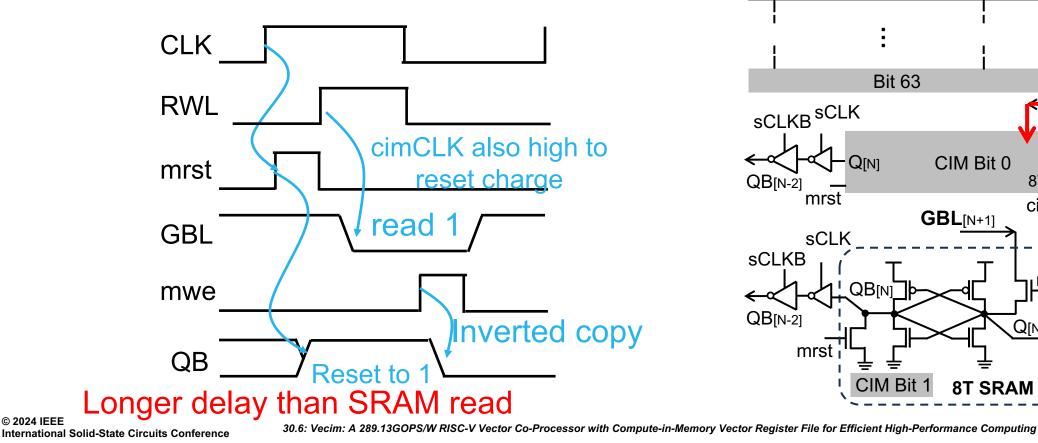


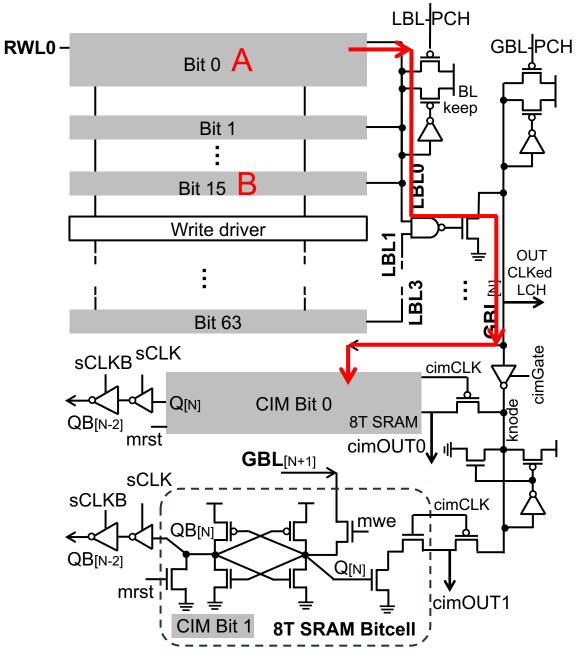
**CIM VRF Circuit and dataflow** 

□ Copy operand A to CIM BIT 0

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In-memory inverted copy operation



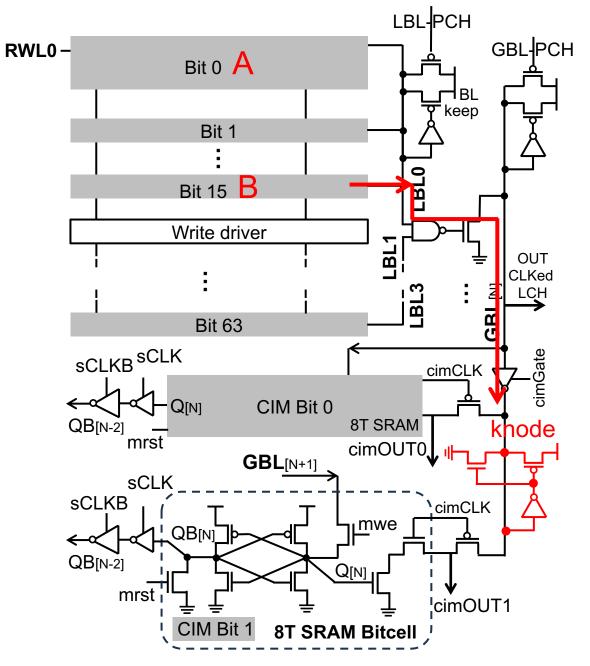


CIM VRF Circuit and dataflow

Copy operand A to CIM BIT 0

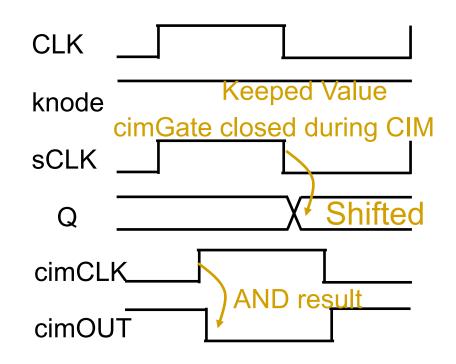
In-memory inverted copy operation

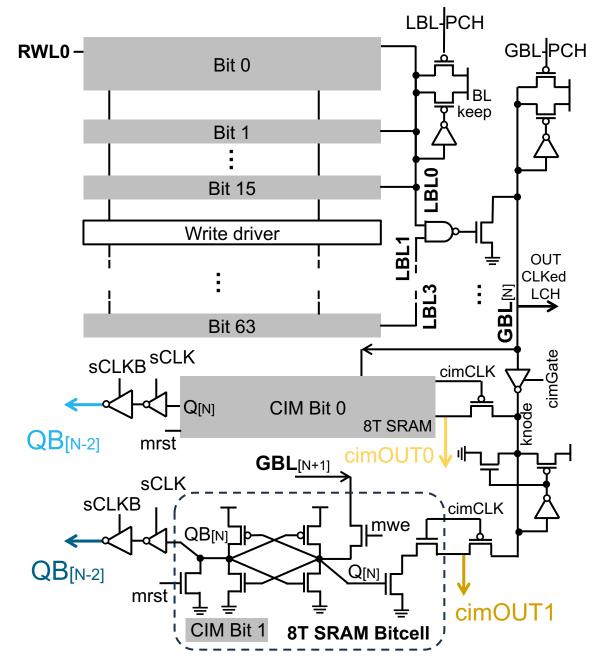
□ Keep operand B at knode



CIM VRF Circuit and dataflow

- In-memory shift
- BL multiplication

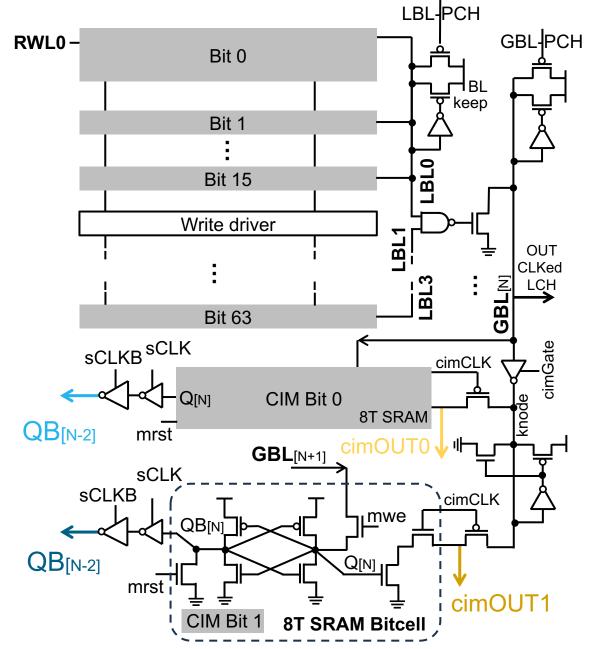




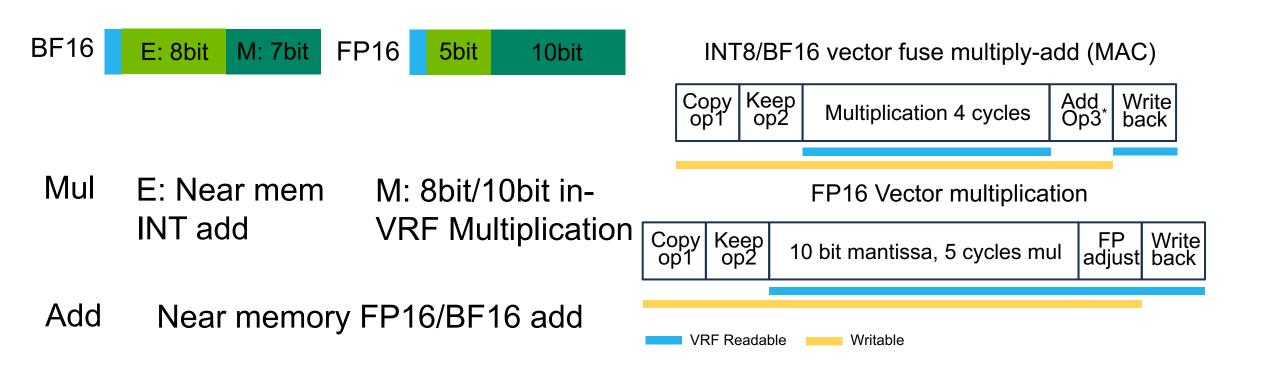
CIM VRF Circuit and dataflow

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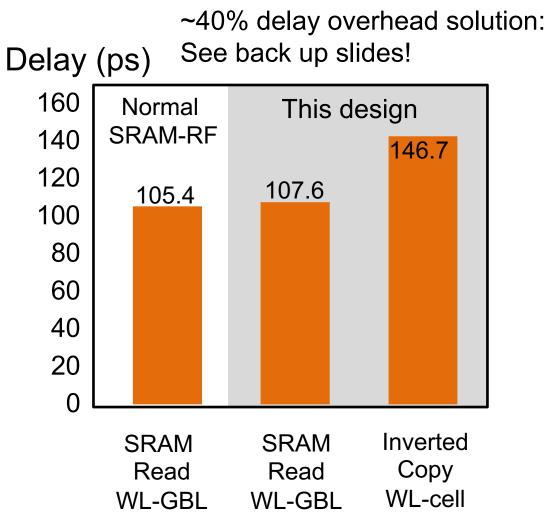


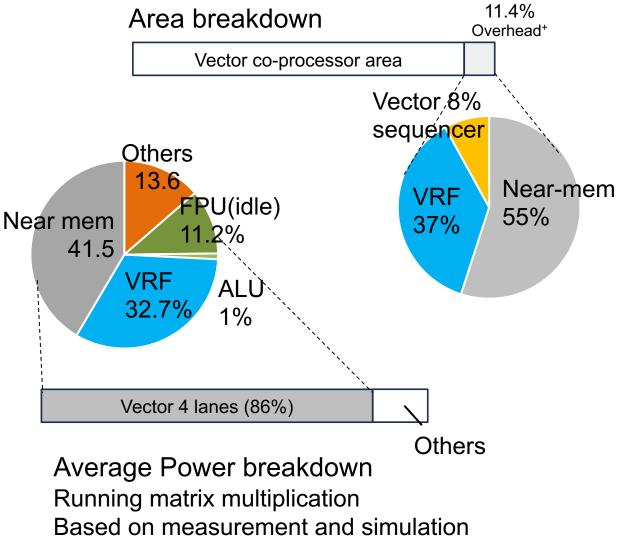


Floating point support with near memory adders

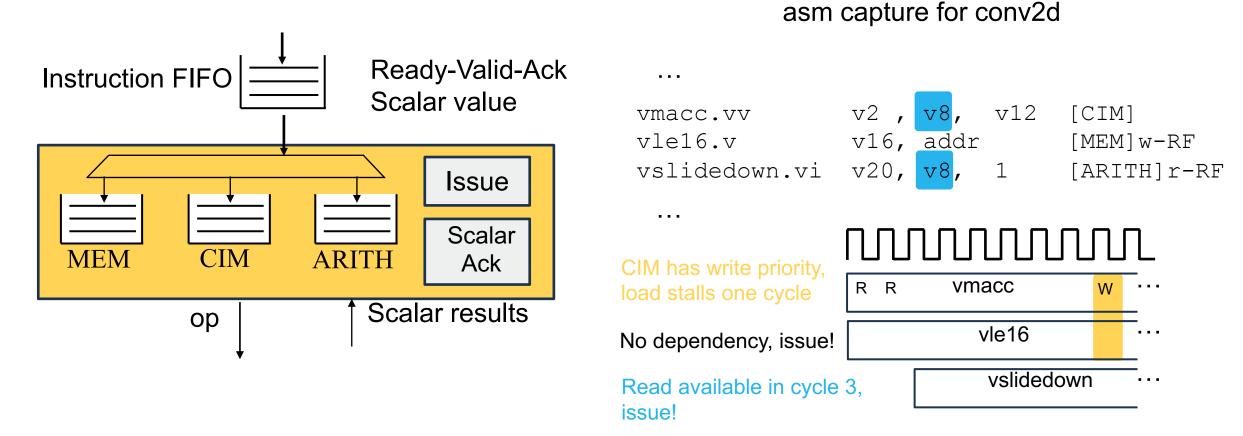


#### PPA and area overhead





#### **Vector Sequencer**



3 queues for memory load/store, CIM related, and other arithmetic instruction
Light-weight out-of-order execution

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Summary

#### **Emerging Matrix Multiplication Application**

Deep learning: CNN, Transformer

Combinatorial optimization: SAT, Ising, ILP

Solve Max-SAT using matrix mul. [David Warde-Farley, Deepmind, Arxiv, 2023]

Security: Kyber, CKKS, TFHE

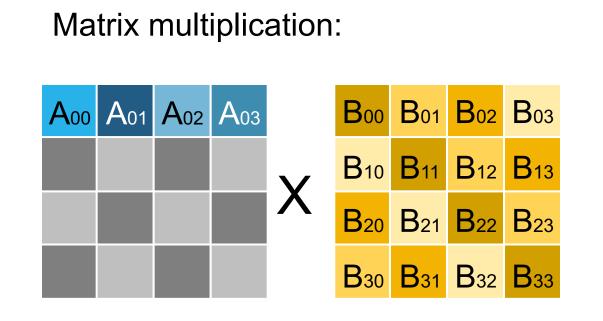
Vector-matrix multiplication in RLWE; TFHE key switching

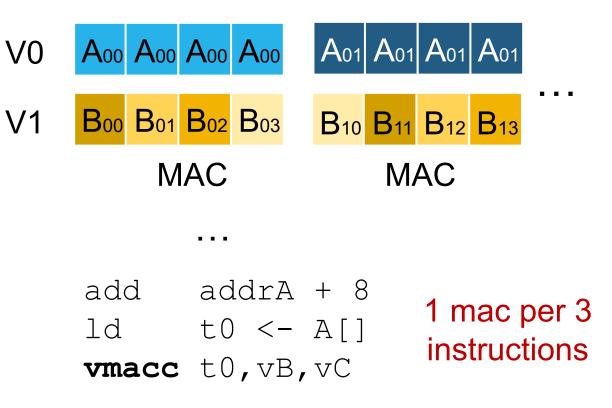
Graphics: NeRF, 3DGS

Matrix multiplication in NeRF: NLP; 3DGS: View transformation

#### **GEMM / MVM algorithm and Instruction extension**

Reuse A:

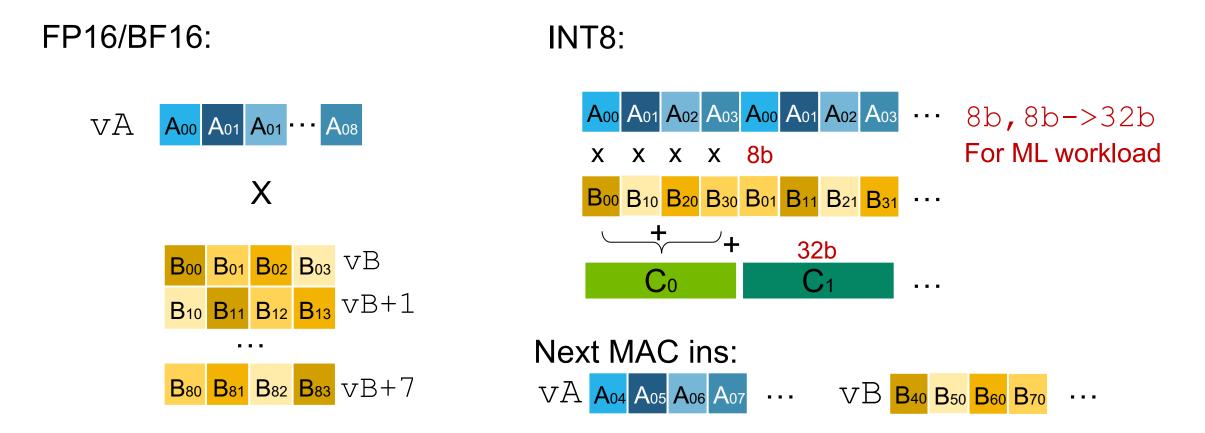




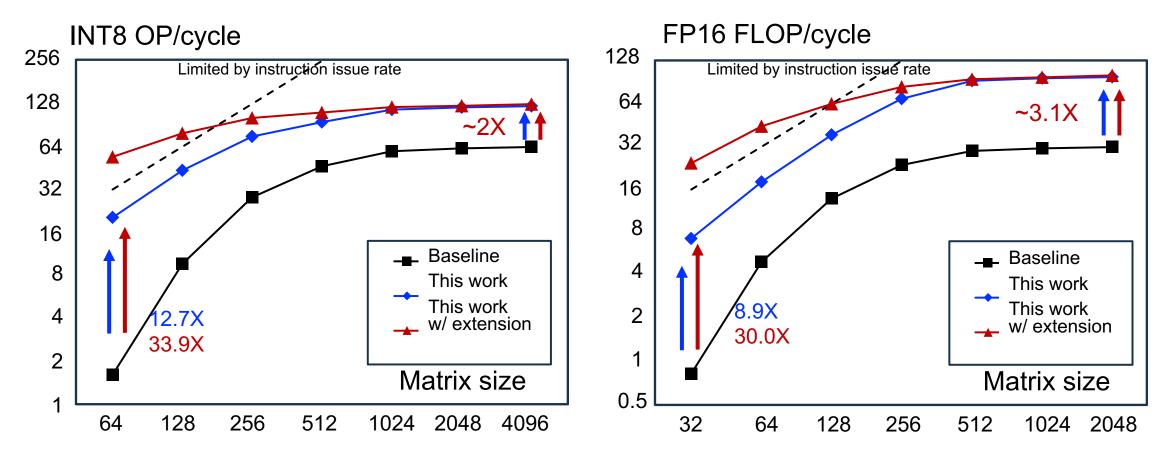
• Reuse A: Instructions bottleneck

#### **GEMM / MVM algorithm and Instruction extension**

#### Instruction extension

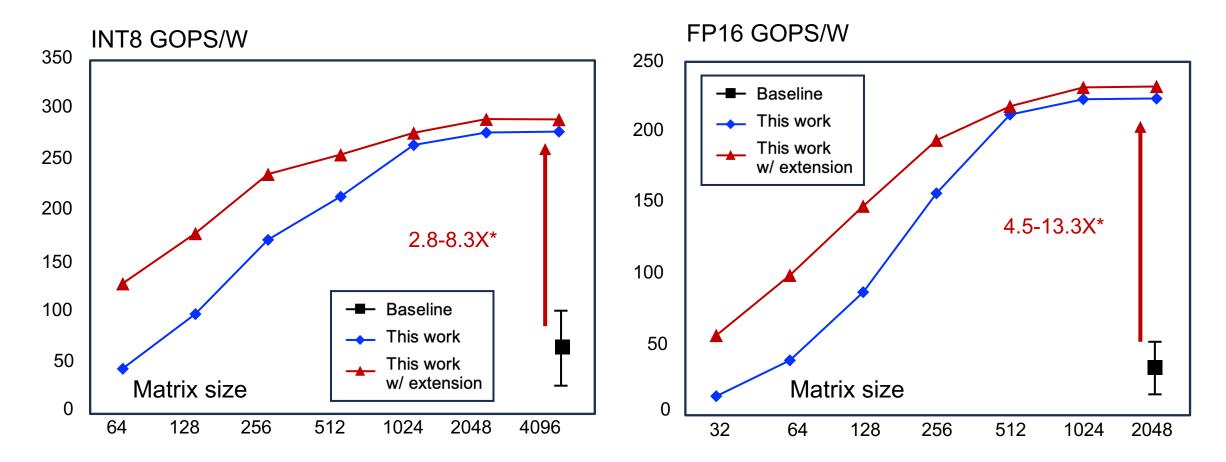


#### **Throughput measurement**



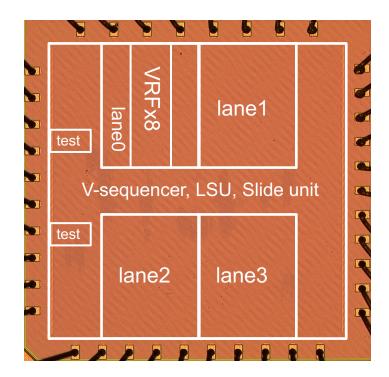
Average throughput measurements running matrix multiplication tasks.

#### Efficiency measurement with average power



\*the min and max point corresponding to power  $\propto$  tech<sup>2</sup> (pessimistic) and  $\propto$  tech (optimistic) normalization. Power measurement is the average of the power curve running matrix multiplication tasks. This work does not count CPU power.

#### **Die shot and chip summary**



Chip summary				
Technology	65nm			
Supply voltage	1V			
Die size	2x2 mm <sup>2</sup>			
Frequency	250MHz			
Precision	All			
	(INT8/BF16/FP16 in			
	memory)			
VRF size	4 lanes x 8 banks x 4kb			
Bit cell area	1.658 um <sup>2</sup>			
Performance	31.8 / 25.3 GOPS			
Energy efficiency	289.13 / 230.10			
	G(FL)OPS/W			
Area efficiency	ncy 7.95 / 6.33 GOPS/mm <sup>2</sup>			

#### **Comparison table**

\*1: 256x256 size matrix multiplication, unless noted; \*2: Use power  $\propto$  tech<sup>2</sup>, this may be pessimistic for advanced nodes. \*3: This is optimistic since there's no pads. \*4: calculated by 1:1 mul/add efficiency x reported CPU mode power.

	Ara [2]	ISSCC 2019 [5]	VLSI 2023 [6]	This work
Technology	GF 22nm	TSMC 28nm	TSMC 65nm	TSMC 65nm
ISA	RISCV	Customed	Customed	RISCV
Category	General purpose processor	Customed CIM design with general purpose operations		General purpose processor
CIM type	-	Custom 8T	Custom 8T/9T	Foundry 8T
Bit precision	All	All (potentially)	INT8/32	All (INT8/BF16/FP16 enhanced)
Design level	Processor (simulation)	Macro + ctrl	Macro + ctrl	Co-processor
Peak performance INT8/FP16 <sup>*1</sup> (CLK frequency is different)	78.4 / 39.2 G(FL)OPS	40.5 / ~0.5 G(FL)OPS	2.3 <sup>*4</sup> / X GOPS	31.8 / 25.3 G(FL)OPS
Throughput (GOPS/MHz)	0.063 / 0.031	0.085 / ~	0.012 / X	0.127 / 0.101
Energy efficiency INT8/FP16 (power normalized to 65nm <sup>*2</sup> )	34.64 / 17.32 G(FL)OPS/W	439.78 / ~5 G(FL)OPS/W	473.35 (GP mode) 7620 (DNN mode) / X GOPS/W	289.13/230.10 G(FL)OPS/W

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### Summary

- Demonstrate SRAM Compute-in-memory in RISCV vector processor register file.
- The 1R1W 8T SRAM register file uses foundry cell with digital CIM and near memory compute unit.
- Achieves 289.13GOPS/W and 7.95GOPS/mm<sup>2</sup> for INT8, 230.10GFLOPS/W and 6.33 GOPS/mm<sup>2</sup> for FP16 precision.

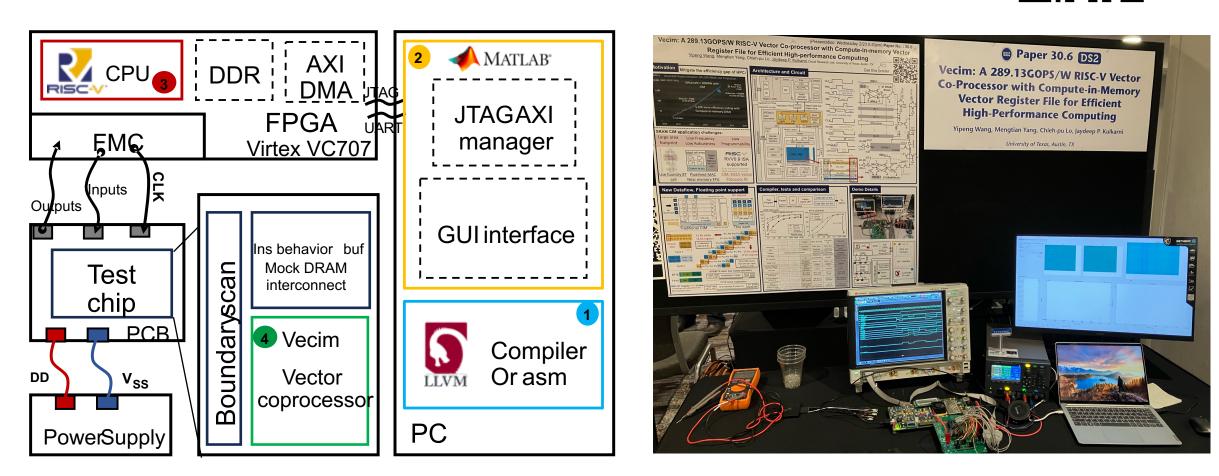
#### Acknowledgments

- TSMC university shuttle support
- UT ECE iMAGINE consortium

# Thank you for your attention!

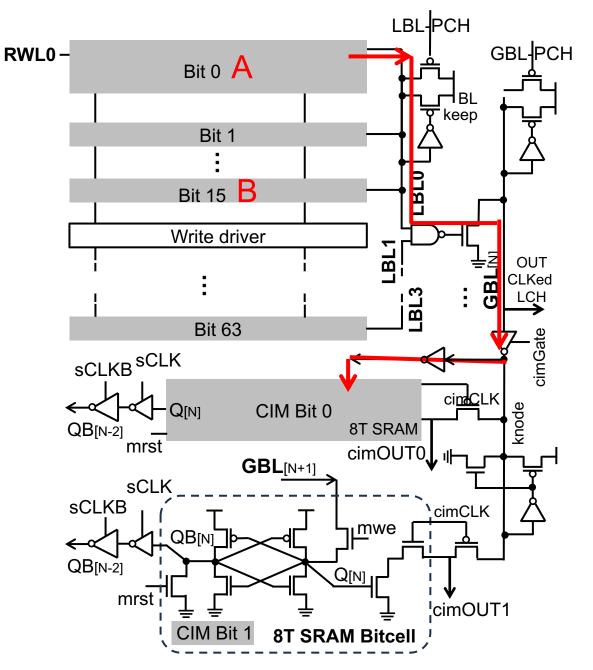


Get the poster

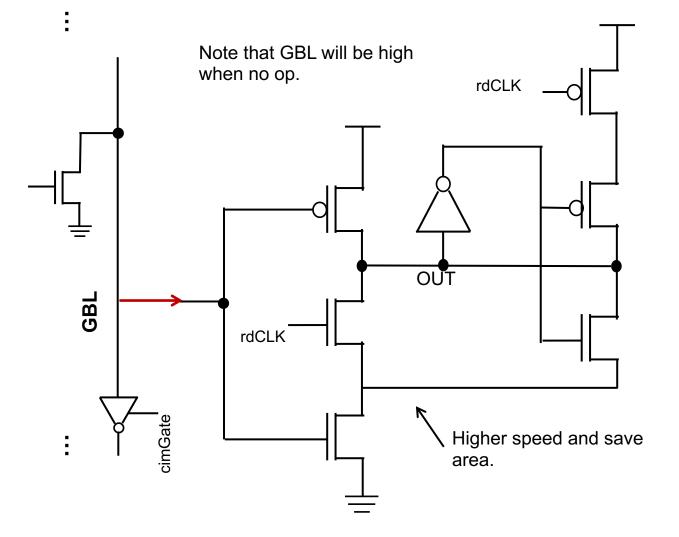


### Solution for slides 24

- Write to CIM bit happens next cycle
- Inverted copy is guaranteed not happen in two consecutive cycles.
- No timing overhead now.
- Some area overhead.

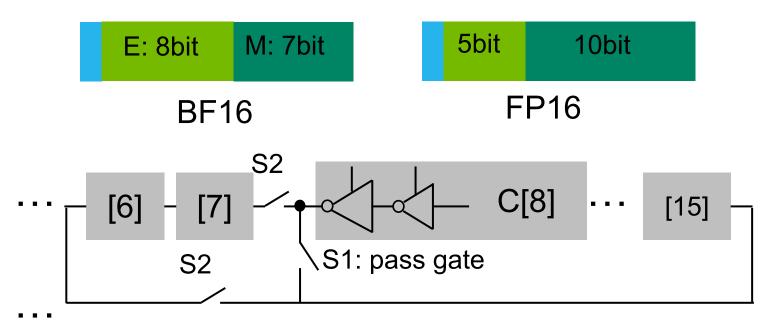


#### **Output CLKed latch**



#### BL / shifter MUX pattern for INT8/BF16/FP16

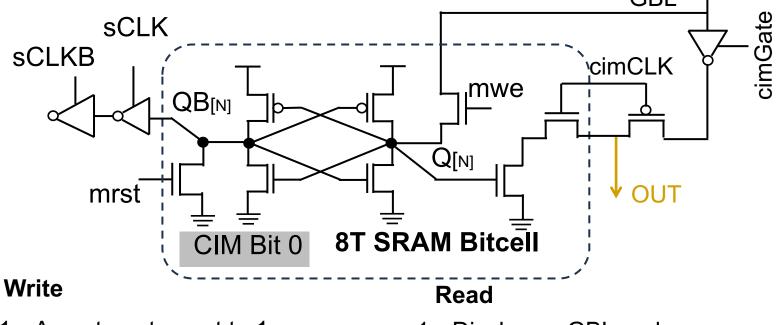
FP16 needs reconfigure 8bit ring shifter to 10bit. We show the MUX pattern here. (GBL is similar)



BF16: S1 closed S2 open, C[8] out disabled; FP16: S1 open S2 closed, E read out for add.

#### **Reuse CIM Bits as renaming physical register**

The CIM Bits can be used as physical register for renaming, We show the normal read/write function here.



- 1. Assert mrst, reset to 1
- 2. Discharge GBL based on data and open mwe

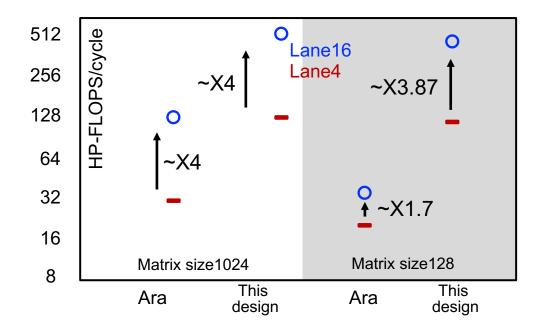
- 1. Discharge GBL and open cimGate
- 2. Toggle cimCLK

Read Write CIM Bits has lower energy and higher performance. This design did not implement register renaming.

#### **Performance scaling simulation**

We show the scalability of this design by increasing the lane numbers and increasing the VRF capacity. The multicore design evaluation is out of our scope.

256



**HP-FLOPS/cycle** This design 128 64 Ara 32 Severe banking conflict 16 FPU all busy, not much improvement 8 Bank size 4 8 16 4

Matrix size 1024

This design scales good with number of lanes on both large and small matrix size.

This design scales simply with VRF size with enough memory bandwidth.